# UNRF2A3

# Silicon NPN epitaxial planar type

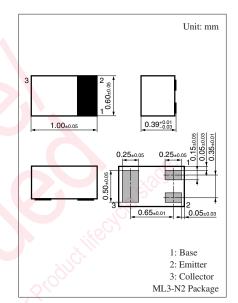
For digital circuits

#### Features

- Reduction of assembly cost and package size with 1006 type mold leadless package is possible
- Maximum package height (0.4 mm) contributes to develop thinner equipments

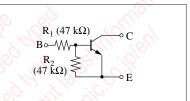
#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | 50          | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | 50          | V    |  |
| Collector current                     | I <sub>C</sub>   | 80          | mA   |  |
| Total power dissipation               | P <sub>T</sub>   | 100         | mW   |  |
| Junction temperature                  | Tj               | 125         | °C   |  |
| Storage temperature                   | T <sub>stg</sub> | -55 to +125 | °C   |  |



Marking Symbol: 1W

#### Internal Connection



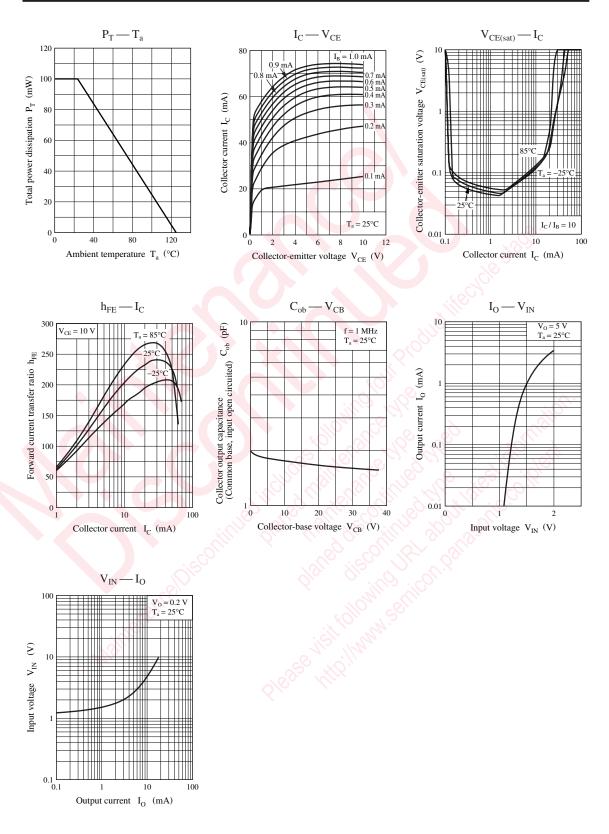
### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

| Parameter                                    | Symbol                          | Conditions   | Min  | Тур | Max  | Unit |
|--|---------------------------------|--|------|-----|------|------|
| Collector-base voltage (Emitter open)        | V <sub>CBO</sub>                | $I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$  | 50   |     |      | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>                | $I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$  | 50   |     |      | V    |
| Collector-base cutoff current (Emitter open) | I <sub>CBO</sub>                | $V_{CB} = 50 \text{ V}, I_E = 0$   |      |     | 0.1  | μΑ   |
| Collector-emitter cutoff current (Base open) | I <sub>CEO</sub>                | $V_{CE} = 50 \text{ V}, I_B = 0$   |      |     | 0.5  | μΑ   |
| Emitter-base cutoff current (Collector open) | I <sub>EBO</sub>                | $V_{EB} = 6 V, I_C = 0$  |      |     | 0.1  | mA   |
| Forward current transfer ratio               | h <sub>FE</sub>                 | $V_{CE} = 10 \text{ V}, \text{ I}_{C} = 5 \text{ mA}$                                    | 80   |     |      |      |
| Collector-emitter saturation voltage         | V <sub>CE(sat)</sub>            | $I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0.3 \text{ mA}$                                  |      |     | 0.25 | V    |
| Output voltage high-level                    | V <sub>OH</sub>                 | $V_{CC} = 5 \text{ V}, \text{ V}_{B} = 0.5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega$ | 4.9  |     |      | V    |
| Output voltage low-level                     | V <sub>OL</sub>                 | $V_{CC} = 5 \text{ V},  \text{V}_{B} = 3.5  \text{V},  \text{R}_{L} = 1  \text{k}\Omega$ |      |     | 0.2  | V    |
| Input resistance                             | R <sub>1</sub>                  |  | -30% | 47  | +30% | kΩ   |
| Resistance ratio                             | R <sub>1</sub> / R <sub>2</sub> |  | 0.8  | 1.0 | 1.2  | _    |
| Transition frequency                         | f <sub>T</sub>                  | $V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$                        |      | 150 |      | MHz  |

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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